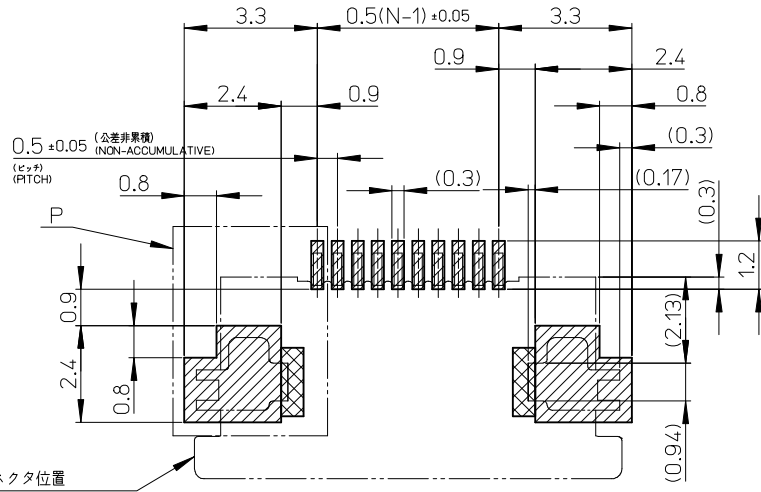


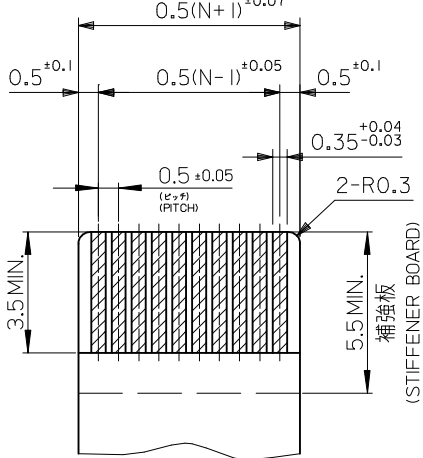
30.5	29.3	25.65	24.5	54132-5062	50
28.0	26.8	23.15	22.0	54132-4562	45
27.0	25.8	22.15	21.0	54132-4362	43
25.5	24.3	20.65	19.5	54132-4062	40
24.5	23.3	19.65	18.5	54132-3862	38
23.5	22.3	18.65	17.5	54132-3662	36
23.0	21.8	18.15	17.0	54132-3562	35
22.5	21.3	17.65	16.5	54132-3462	34
22.0	20.8	17.15	16.0	54132-3362	33
21.5	20.3	16.65	15.5	54132-3262	32
20.5	19.3	15.65	14.5	54132-3062	30
D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	CKT.

CONNECTOR SERIES NO. : 54132-\*\*68

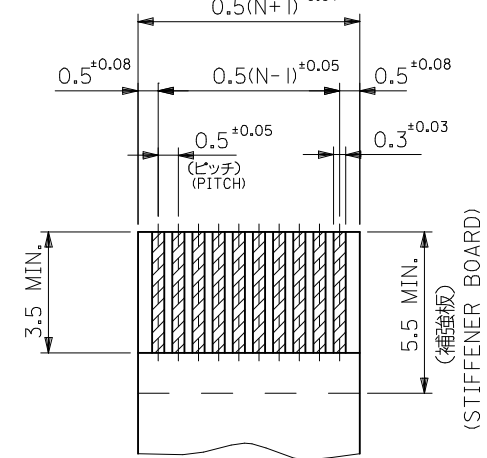
REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT NI-BARRIER GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004/09/27	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-54132-064	SHEET NO. 1 OF 2
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



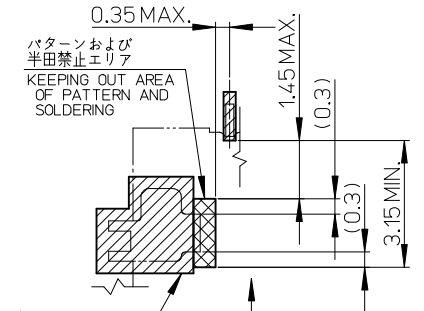
参考基板レイアウト  
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)  
(マウント面)  
(MOUNTING SIDE)



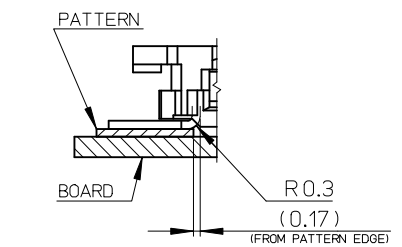
適合金めっきFPC推奨寸法  
APPLICABLE FPC OF GOLD PLATING  
RECOMMENDED DIMENSION  
(仕上がり厚さ : 0.3±0.03)  
(THICKNESS : 0.3±0.03)



適合金めっきFFC推奨寸法  
APPLICABLE FFC OF GOLD PLATING  
RECOMMENDED DIMENSION  
(仕上がり厚さ : 0.3±0.03)  
(THICKNESS : 0.3±0.03)



DETAIL P



VIEW R  
(DETAIL OF FITTING NAIL ON PATTERN)

注記 NOTES

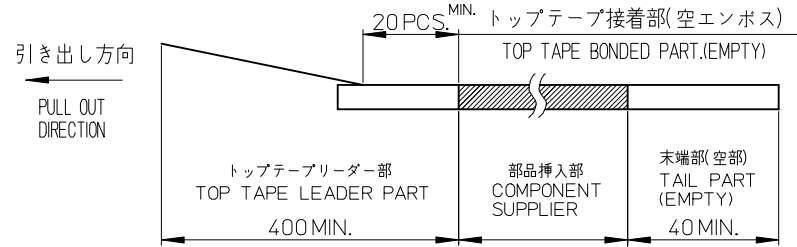
- 1.使用材料 MATERIAL  
ハウジング : 46ナイロン、ガラス充填、UL94V-0、白  
HOUSING:PA46,GLASS FILLED,UL94V-0,WHITE  
アクチュエータ:ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒  
ACTUATOR:POLYPHENYLENE SULFIDE,GLASS FILLED,UL94V-0,BLACK  
ターミナル : リン青銅(≒0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM  
テール部 0.05 MICROMETER MINIMUM  
ニッケル下地 1.0 MICROMETER MINIMUM  
TERMINAL PHOS-BRONZE GOLD-PLATING  
CONTACT PORTION : 0.1 MICROMETER MINIMUM  
TAIL PORTION : 0.05 MICROMETER MINIMUM  
NICKEL PLATING : 1.0 MICROMETER MINIMUM  
金具 : リン青銅(≒0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM  
ニッケル下地 1.0~3.0 MICROMETER MINIMUM  
FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM  
OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
- 2.エンボステーパ梱包時はアクチュエータがロックした状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.54132-\*\*68 SHOULD BE LOCKED.  
ソルダータール半田付け面のズレ量、および金具半田付け面のズレ量は  
基準面  $\square$  に対し上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする。  
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM  $\square$   
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

- △ 偶数極に適用。  
APPLY FOR EVEN CIRCUIT.
  - △ パターンはく離止め金具。  
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.BOARD PATTERN.
  - 6.本製品は54132-\*\*61に対するニッケルバリア品になります。  
THIS PRODUCT IS NICKEL-BARRIER OF 54132-\*\*61.
  - 7.ELV & RoHS適合品。  
ELV AND ROHS COMPLIANT.
- FPC/FFCについて :  
打ち抜き方向は導体側から補強板側を推奨いたします。  
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします。  
RECOMMENDED PUNCHER DIRECTION  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED CONDUCTOR SPEC  
THICKNESS OF SOFT COPPER FOIL : 35MICROMETERS OR 50MICROMETERS
- FPCについて :  
補強フィルム材質はポリイミドを推奨いたします。  
接着剤は熱硬化接着剤を推奨いたします。  
RECOMMENDED MATERIAL  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

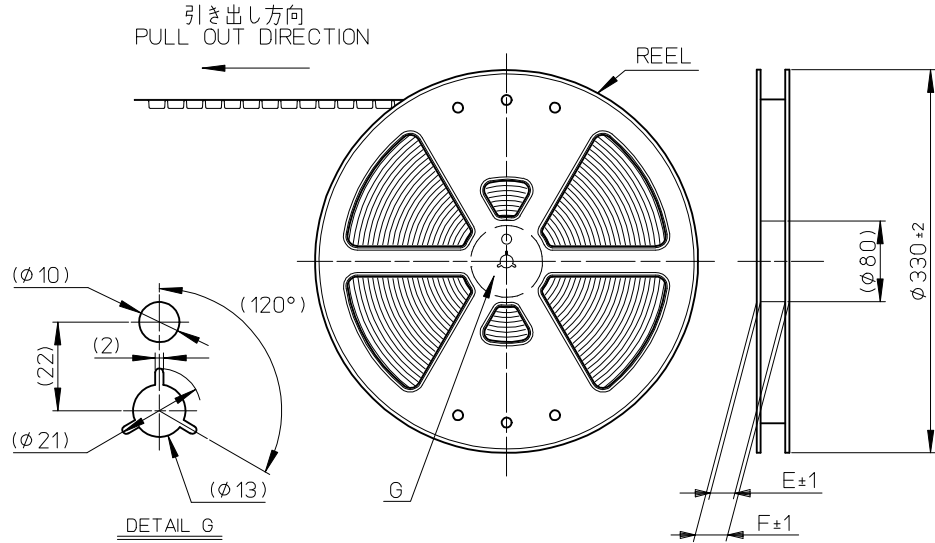
REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APP:R.KMORI/KAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT NI-BARRIER GOLD PLATING		
	10 OVER 30 UNDER	± ---	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY N.UKITA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064		
	ANGULAR ± --- °	MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTE

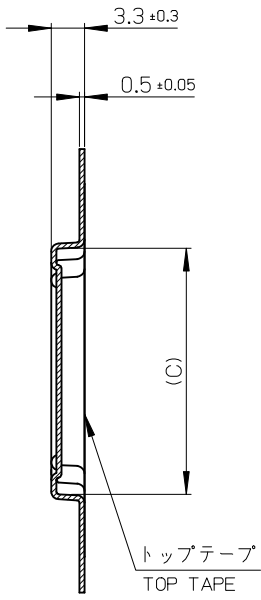
- 1. 梱包数量 : 1500個/リール  
NUMBER OF CONNECTORS : 1500PCS/REEL
- 2. リードテープ長さ  
LEAD TAPE LENGTH



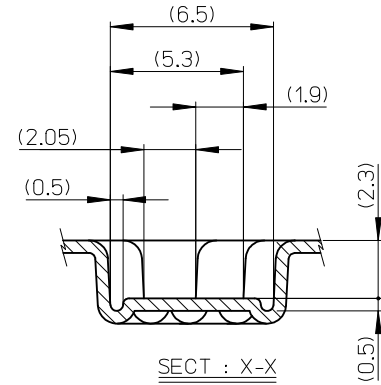
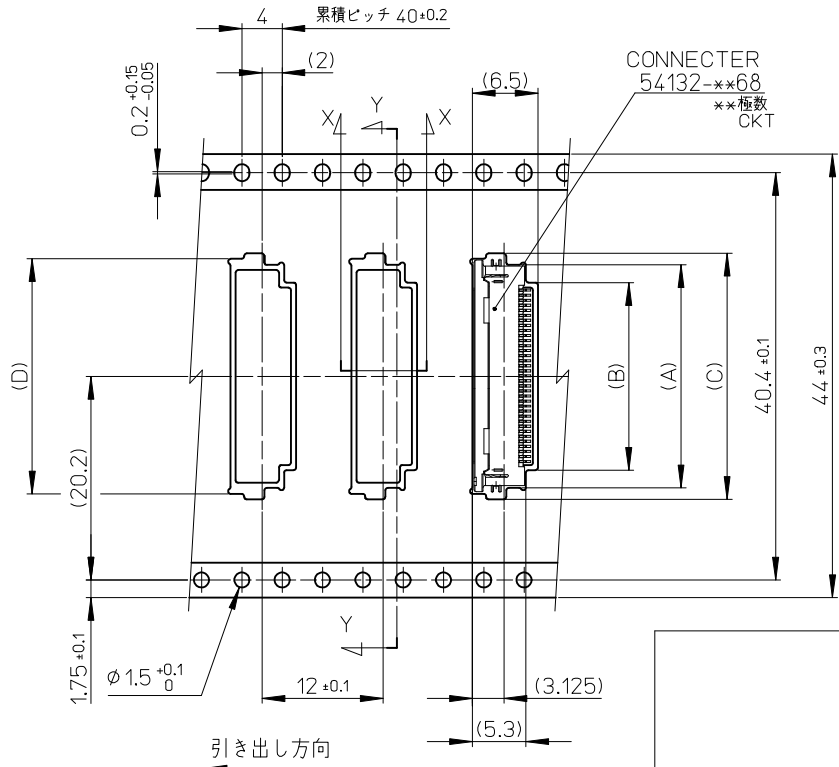
- 3. カバーテープの はく離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
- 4. 材料 キャリアテープ : ポリプロピレン(PP)  
トップテープ : PET,PE,PEF  
リール : ポリスチレン(PS) <リサイクル材を含む>  
MATERIAL CARRIER TAPE : POLYPROPYLENE  
TOP TAPE : PET,PE,PEF  
REEL : POLYSTYRENE<RECYCLE MATERIAL CONTAINED>
- 5. ELV & RoHS適合品  
ELV AND RoHS COMPLIANT



RELEASED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/13 CHKD:HIIJIMA 2010/07/13 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±---	DRAWN BY HYOSHINO	DATE 2010/07/13	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT TAPING PACKAGE			
	10 OVER 30 UNDER	±---	CHECKED BY HIIJIMA	DATE 2010/07/13	MOLEX INCORPORATED			
	30 OVER	±---	APPROVED BY KMORIKAWA	DATE 2010/07/16	DOCUMENT NO. SD-54132-065		SHEET NO. 1 OF 2	
0	DESCRIPTION ANGULAR ±--- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



SECT : Y-Y



44	49.4	45.4	30.8	31.9	26.1	29.6	54132-5062	50		
			28.3	29.4	23.6	27.1	54132-4562	45		
			27.3	28.4	22.6	26.1	54132-4362	43		
			25.8	26.9	21.1	24.6	54132-4062	40		
			24.8	25.9	20.1	23.6	54132-3862	38		
			23.8	24.9	19.1	22.6	54132-3662	36		
			23.3	24.4	18.6	22.1	54132-3562	35		
			22.8	23.9	18.1	21.6	54132-3462	34		
			22.3	23.4	17.6	21.1	54132-3362	33		
			21.8	22.9	17.1	20.6	54132-3262	32		
20.8	21.9	16.1	19.6	54132-3062	30					
キャリアテープ幅 CARRIAR TAPE WIDTH			F	E	D	C	B	A	MATERIAL NO. (EMBOSS PKG)	CKT.

RELEASED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/13 CHKD:HIIJIMA 2010/07/13 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY HYOSHINO	DATE 2010/07/13	TITLE 0.5 FPC CONN. ZIF SMT R/A BOTTOM CONTACT TAPING PACKAGE			
	10 OVER 30 UNDER	± ---	CHECKED BY HIIJIMA	DATE 2010/07/13	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/07/16	DOCUMENT NO. SD-54132-065		SHEET NO. 2 OF 2	
	ANGULAR ± --- °		MATERIAL NO. SEE SHEET		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								